



ATCPZ003-UUDM-T - 4L WLCSP - SAC

Package Information

Assy Site :	ASE - ASE Inc
Part Number :	ATCPZ003-UUDM-T
Package :	GBB - 4L WLCSP - (Wafer Level Chip Scale Package)
Lead Finish/Industry Standard :	SAC / JEDEC (e1)

Material List

Material	Type	Manufacturer
Plating & Anode Ball	SAC405 (7097)	SENJU
Substrate	HD-8820	HITACHI
Substrate	Ti_3N	UMICORE
Substrate	Cu 4N5	UMICORE
Substrate	LC2850	LINTEC
Wafer	AlSiCu Wafer	GRSM
Wafer	Cu Wafer	UMC
Wafer	Al Wafer	UMC